HYCLEANSE® 385

Entec Polymers - Thermoplastic

Wednesday, November 6, 2019

General Information

Product Description

HYCLEANSE-385 Purge is a multipurpose, binary engineered thermoplastic purging compound, formulated for blown film equipment. HyCleanse-385 Purge is a cleansing compound specially tailored for most resins that are utilized in sheet and film extrusion processes. HyCleanse-385 Purge contains several proprietary additives used to maximize thermal stability and reduce degradation and oxidative by-products occurring during the manufacturing process as well other contaminants produced in most olefinic resin processes.

Features and Benefits:

HyCleanse-385 Purge is easy to use and no process changes are needed. Use at the normal resin processing temperature and RPM speed. No mixing is required.

Applications: Blown film - Cast film

Types of Resins: PE, PP, and PS

General

Material Status	• Commercial: Active
Availability	• North America
Additive	• Proprietary
Uses	• Purging Compound
Agency Ratings	• FDA Unspecified Rating

ASTM & ISO Properties [1]

Physical	**Nominal Value**	**Unit**
Density	0.955	g/cm³
Additional Information	**Nominal Value**	**Unit**
Temperature Range	350 to 450	°F

Notes

[1] Typical properties: these are not to be construed as specifications.